innovation by design

TECHNICAL DATA SHEET

LOW ESD POLYIMIDE FILM TAPE

DESCRIPTION

Manufactured from 1 mil thin polyimide film with 2.4 mils anti-static silicone adhesive. The ESD function can reduce the discharge of electroplating static upon tape removal.

APPLICATION

Chosen for protecting gold finger of PCB during wave soldering process.

PRODUCT BENEFITS

- Safe and clean removal from PCB.
- High conformability

TECHINICAL DATA

Item	Test Method	Normal	Min.
Adhesive		Silicone	
Backing		Polyimide Film	
Carrier Thickness (mil/mm)	ASTM D 1000	1.00 / 0.025	
Total Thickness (mil/mm)	ASTM D 1000	3.39 / 0.085	3.27 / 0.082
Color		Amber	
Adhesion to Steel (N/25mm)/(g/25mm)/(oz/in)	ASTM D 1000	7.3 / 750 / 26.5	6.8 / 600 / 24.4
Tensile Strength (N/25mm)/(kg/25mm)/(lb/in)	ASTM D 1000	98 / 10 / 21.7	88 / 9.0 / 20
Dielectric Strength (kV)	ASTM D 149	7.0	6.5
Insulation Resistance (ohms)	ASTM D 257	$>10^6$	
Class of Insulation (C)	UL 510	UL H / 200	
Elongation (%) Static Charge-Unwinding (Volt)	ASTM D 1000	50 <50	40 5
Range of Temperature (C/F)		-73~260 / -100~500	

The above values are typical values and should be used only as a guide. Due to the nature of process variables, Echo makes no warranty or guarantee on the use of this product in a specific process and user should always test material in their own process before running production.